

Docket No. 10936-66

PATENT**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on August 7, 2002.

Linda Drake**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

Applicant: Hideki Kitamura et al : Paper No.:

Serial No.: 10/019,858 : Group Art Unit: 1752

Filed: November 9, 2001 : Examiner:

For: **Semiconductive Polyvinylidene Fluoride Resin Composition**

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56 and 1.97-1.98, Applicants cite and submit copies of the references listed on the attached Form PTO-1449. These references were cited in the corresponding European application in a Supplementary Search Report dated July 19, 2002 (copy enclosed). EP 942038 corresponds with JP 11-323052 cited in Applicant's previous Information Disclosure Statement filed April 12, 2002.

As the present Statement is submitted prior to a first official action, no statement or fee under 37 CFR 1.97 is required.

Respectfully submitted,

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FORM PTO-1449
LIST OF PATENTS AND PUBLICATIONS
FOR APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

ATTY. DOCKET 10936-66 **SERIAL NO.** 10/019,858
APPLICANT Hideki Kitamura et al
FILING DATE November 9, 2001 **GROUP** 1752
FOR Semiconductive Polyvinylidene Fluoride Resin Composition

UNITED STATES LETTERS PATENT

FOREIGN PATENT DOCUMENTS

OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

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EXAMINER DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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